

Reliability Summary Report

Product Type: 16Gb (1Gx16) DDR4

16Gb (2Gx8) DDR4

Part Number: KTD MAG4B632BGCBA

KTD MAG4B632BGIBA

KTD MAG4B832BGCBA

KTD MAG4B832BGIBA

Package: 96 ball BGA

78 ball BGA

1. Features

- Power supply (JEDEC standard 1.2V)
 - VDD = 1.2V ± 5%
 - VPP = 2.375V to 2.75V
- 16 internal banks – 16 banks (4 banks x 4 bank groups) for x8 product
- 8 internal banks - 8 banks (4 banks x 2 bank groups) for x 16 product
- Interface: Pseudo Open Drain (POD)
- Burst Length (BL): 8 and 4 with Burst Chop (BC)
- CAS Latency (CL): 10,(11),12,(13),14,(15),16,(17),18,19,20,22,24
- CAS Write Latency (CWL): 9,10,11,12,14,16,18,20
- On-Die Termination (ODT): nom. values of RZQ/7, RZQ/5 (RZQ = 240Ω)
- Precharge: auto precharge option for each burst access
- Refresh: auto-refresh, self-refresh
- Refresh cycles
 - Average refresh period
 - 7.8μs at 0°C ≤ TC ≤ +85°C or -40°C ≤ TC ≤ +85°C
 - 3.9μs at +85°C < TC ≤ +95°C
- Double-data-rate architecture: two data transfers per clock cycle
- The high-speed data transfer is realized by the 8 bits prefetch pipelined architecture
- Bi-directional differential data strobe (DQS_t and DQS_c) is transmitted/received with data for capturing data at the receiver
- DQS is edge-aligned with data for READs; center aligned with data for WRITEs
- Differential clock inputs (CK_t and CK_c)
- DLL aligns DQ and DQS transitions with CK transitions
- Commands entered on each positive CK edge; data and data mask referenced to both edges of DQS
- Data Mask (DM) for write data
- Write Cyclic Redundancy Code (CRC) for DQ error detect and inform it to controller during high-speed operation

- Data Bus Inversion (DBI)
 - Improve the power consumption and signal integrity of the memory interface (x16 product only)
- Programmable preamble is supported both of 1tCK and 2tCK mode
- Command Address (CA) Parity for command/address signal error detect and inform it to controller
- VREFDQ training
 - VREFDQ generate inside DRAM and further train per DRAM
- Per DRAM Addressability (PDA)
 - Each DRAM can be set a different mode register value individually and has individual adjustment.
- Fine granularity refresh
 - 2x, 4x mode for smaller tRFC
- Programmable Partial Array Self-Refresh (PASR)
- RESET_n pin for power-up sequence and reset function
- Operating case temperature range:
 - Commercial: $T_C = 0^{\circ}\text{C}$ to $+95^{\circ}\text{C}$
 - Industrial: $T_C = -40^{\circ}\text{C}$ to $+95^{\circ}\text{C}$

2. Package Information

Product No.	VDD	Data Rate (CL-tRCD-tRP)	Package	Temperature	Comments
KTDMAG4B632BGCBA	1.2V	DDR4-3200 (22-22-22)	96 ball BGA	Commercial	Pb-free
KTDMAG4B632BGIBA	1.2V	DDR4-3200 (22-22-22)	96 ball BGA	Industrial	Pb-free
KTDMAG4B832BGCBA	1.2V	DDR4-3200 (22-22-22)	78 ball BGA	Commercial	Pb-free
KTDMAG4B832BGIBA	1.2V	DDR4-3200 (22-22-22)	78 ball BGA	Industrial	Pb-free

Note:

The above description is extracted from the datasheet. Please refer to the document for detailed information.

3. Product Qualification Tests

3.1. Environmental Tests

No.	Item	Condition	Sample Size	Results
1	Pre-Conditioning	JESD22-A113/JESD-020 (MSL 3) (bake 24h+TH 60°C/60% 52h+reflow 3x)	304	Passed
2	TC (Temperature Cycling)	JESD-22-A104E (-55°C to 125°C, no bias), up to 600 cycles	76	Passed
3	THB (Temperature & Humidity with Bias)	JESD22-A101D (85°C/85% with bias), up to 1000h	76	Passed
4	uHAST	JESD22-A111B (130°C/85%/1 atm, no bias), up to 168h	76	Passed
5	HTS (High Temperature Storage)	JESD22-A103E (150°C, no bias), up to 1000h	76	Passed
6	MSL Reclassification	JESD-020, MSL3 (SAT+bake 24h+TH 60°C/60% 52h+reflow 3x+SAT)	33	Passed

3.2. Operating, ESD & Latch-up Tests

No.	Item	Condition	Sample Size	Results	
1	High Temperature Operating Life (HTOL)	JESD22-A108F (125°C, Dynamic Stress) up to 300h	76	Pass	
2	Low Temperature Operating Life (LTOL)	JESD22-A108F (-10°C, Dynamic Stress) up to 300h	76	Pass	
3	ESD	HBM	JESD-A114F (2kV)	40	Pass
		CDM	JESD22-C101F (500V)	30	Pass
4	Latch-Up	V-test	JESD78E (6V/2.94V)	10	Pass
		I-test	JESD78E (150mA)	40	Pass